ABSTRACT

A sticking apparatus 15 includes a sticking table 40 that supports a semiconductor wafer W, a sticking unit 41 that sticks a heat sensitive adhesive sheet S, and a cutter 96 that cuts the adhesive sheet for each semiconductor wafer in the width direction and in the periphery direction. The tables include a sticking table 40 that is controlled to a first temperature at which the adhesive sheet S is temporarily stuck to the wafer W, a periphery cutting table 47 that is controlled to a second temperature at which the viscosity of the adhesive sheet is reduced and cuts the adhesive tape in the peripheral direction, and a sticking table 48 that is controlled to a third temperature at which the adhesive sheet S is completely stuck to the wafer W.